IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIE	Material Compos © Copyright 2005. IPC international and Pan-A	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Form Type Distribute					* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi				rials and M	ials and Mfg Information			
upplier Inforn	nation													
Company name*			Company unique ID			Ţ	Unique ID Authority				Response Date*			
nsemi										2024-05	2024-05-03			
Contact Name		Title - Contact			I	Phone - Contact*				Email -	Email - Contact*			
Product-Env-Stewa	ards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			I	Phone - Representative*				Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Request	Requester Item Number		Number	Mfr Item Name			Effective Date	e Versio	on I	Manufacturing Site		Weight*	UOM	Unit Type
		FDMS007N08LC FET 80V 6.7		FET 80V 6.7 mOl	.7 mOhm PQFN56		2024-05-03 PBB		'BB		109.07974	mg	Each	
Ianufacturing	Process Information	on												
Terminal Plating / Grid Array Material T			Terminal Base Alloy J-STD-020 MSI		SL Rating	Peak Process Body Temperat		Temperatu	ture Max Time at Peak Tempera		ture Numbe	r of Reflow Cyc	eles	
Matte Tin (Sn) - annealed			CU Alloy 1				260 C 30		30	seconds 3				
omments														
vel 1 - maximum	ime at peak temperature	e during sol	dering is 10-3	30 seconds										
or more informati	on regarding material co	omposition j	please refer t	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier shave provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-6_									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	14.9856	mg	Supplier	Zinc (Zn)	7440-66-6		0.018	mg
			Supplier	Iron (Fe)	7439-89-6		0.3522	mg
			Supplier	Copper (Cu)	7440-50-8		14.611	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0045	mg
Die	2.6048	mg	Supplier	Silicon (Si)	7440-21-3		2.6048	mg
Die Attach Solder	4.2978	mg	Supplier	Silver (Ag)	7440-22-4		0.1074	mg
			A	Lead (Pb)	7439-92-1	7a	3.9755	mg
			Supplier	Tin (Sn)	7440-31-5		0.2149	mg
Lead Frame	45.3136	mg	Supplier	Silver (Ag)	7440-22-4		2.2657	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0544	mg
			Supplier	Iron (Fe)	7439-89-6		1.0875	mg
			Supplier	Copper (Cu)	7440-50-8		41.8698	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0363	mg
Mold Compound-Black	39.5381	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		2.57	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1977	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		34.7935	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.9769	mg
Plating	2.33184	mg	Supplier	Tin (Sn)	7440-31-5		2.3318	mg
Wire Bond - Cu	0.008	mg	Supplier	Palladium (Pd)	7440-05-3		0.0002	mg
			Supplier	Copper (Cu)	7440-50-8		0.0078	mg